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EU adopts regulation on ARTEMIS' joint undertaking

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The ARTEMIS industrial association ARTEMISIA announced that a Council of the European Union has approved the regulation on the setting up of the ARTEMIS Joint Undertaking as the legal embodiment of ARTEMIS Joint Technology Initiative.

PARIS — The ARTEMIS industrial association ARTEMISIA announced that a Council of the European Union has approved the regulation on the setting up of the ARTEMIS Joint Undertaking as the legal embodiment of ARTEMIS Joint Technology Initiative.

Initiated in 2004, ARTEMIS is the European Technology Platform for Advanced Research & Technology for Embedded Intelligence and Systems. Its objective consists in reinforcing European industry's leading position in embedded system technology. The economic impact in terms of jobs and growth is expected to exceed €100 billion over the next ten years.

ARTEMISIA was established on January 2007 to rally European R&D actors so as to collectively represent them in the Joint Technology Initiative on embedded systems. The JTI has been implemented by means of Joint Undertaking on the basis of the EU Treaty, with ARTEMISIA, the European Commission, 18 Member States and Associated States as its members. It features a novel co-financing mechanism for collaborative transnational R&D projects that combines elements of Eureka's ITEA2 and MEDEA+ clusters and those of the Framework Program.

The JTI also leverages private and national investments and aligns Europe's fragmented R&D efforts around a common, pan-European SRA.

At this point, ARTEMISIA has defined eight sub-programs. The first call for project proposals on the basis of these subprograms is expected by the second quarter of 2008.

The total program size is set to reach 2.4 billion euros

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